General Specifications





GENERAL DESCRIPTION

With increased requirements from the automotive industry for additional component robustness, AVX recognized the need to produce a MLCC with enhanced mechanical strength. It was noted that many components may be subject to severe flexing and vibration when used in various under the hood automotive and other harsh environment applications.

To satisfy the requirement for enhanced mechanical strength, AVX had to find a way of ensuring electrical integrity is maintained whilst external forces are being applied to the component. It was found that the structure of the termination needed to be flexible and after much research and development, AVX launched FLEXITERM®. FLEXITERM® is designed to enhance the mechanical flexure and temperature cycling performance of a standard ceramic capacitor with an X7R dielectric. The industry standard for flexure is 2mm minimum. Using FLEXITERM®, AVX provides up to 5mm of flexure without internal cracks. Beyond 5mm, the capacitor will generally fail "open".

As well as for automotive applications FLEXITERM® will provide Design Engineers with a satisfactory solution when designing PCB's which may be subject to high levels of board flexure.

PRODUCT ADVANTAGES

- High mechanical performance able to withstand, 5mm bend test guaranteed
- Increased temperature cycling performance, 3000 cycles and beyond
- Flexible termination system
- · Reduction in circuit board flex failures
- · Base metal electrode system
- · Automotive or commercial grade products available
- · AECO200 Qualified
- Approved to VW 80808 Specification

APPLICATIONS

High Flexure Stress Circuit Boards

· e.g. Depanelization: Components near edges of board.

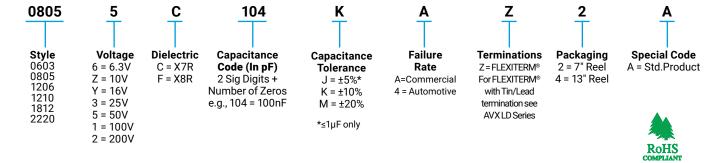
Variable Temperature Applications

- Soft termination offers improved reliability performance in applications where there is temperature variation.
- · e.g. All kind of engine sensors: Direct connection to battery rail.

Automotive Applications

- · Improved reliability.
- Excellent mechanical performance and thermo mechanical performance.

HOW TO ORDER



NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.



Specifications and Test Methods

A KYOCERA GROUP COMPANY

PERFORMANCE TESTING

AEC-Q200 Qualification:

 Created by the Automotive Electronics Council

 Specification defining stress test qualification for passive components

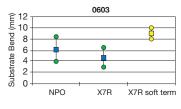
Testing:

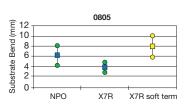
Key tests used to compare soft termination to AEC-Q200 qualification:

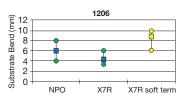
- · Bend Test
- · Temperature Cycle Test

BOARD BEND TEST RESULTS

AEC-Q200 Vrs AVX FLEXITERM® Bend Test







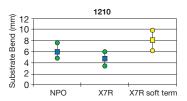


TABLE SUMMARY

Typical bend test results are shown below:

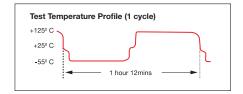
Style	Conventional Termination	FLEXITERM [®]
0603	>2mm	>5mm
0805	>2mm	>5mm
1206	>2mm	>5mm

TEMPERATURE CYCLE TEST PROCEDURE

Test Procedure as per AEC-Q200:

The test is conducted to determine the resistance of the component when it is exposed to extremes of alternating high and low temperatures.

- · Sample lot size quantity 77 pieces
- TC chamber cycle from -55°C to +125°C for 1000 cycles
- Interim electrical measurements at 250, 500, 1000 cycles
- Measure parameter capacitance dissipation factor, insulation resistance



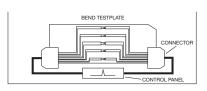
BOARD BEND TEST PROCEDURE

According to AEC-Q200

Test Procedure as per AEC-Q200: Sample size: 20 components

Span: 90mm Minimum deflection spec: 2 mm

- · Components soldered onto FR4 PCB (Figure 1)
- Board connected electrically to the test equipment (Figure 2)



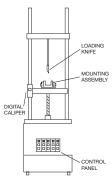


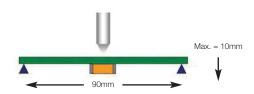
Fig 1 - PCB layout with electrical connections

Fig 2 - Board Bend test equipment

AVX ENHANCED SOFT TERMINATION BEND TEST PROCEDURE

Bend Test

The capacitor is soldered to the printed circuit board as shown and is bent up to 10mm at 1mm per second:



- The board is placed on 2 supports 90mm apart (capacitor side down)
- The row of capacitors is aligned with the load stressing knife



- The load is applied and the deflection where the part starts to crack is recorded (Note: Equipment detects the start of the crack using a highly sensitive current detection circuit)
- The maximum deflection capability is 10mm

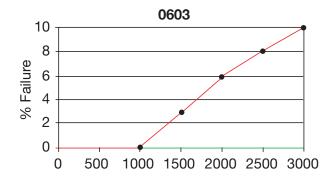


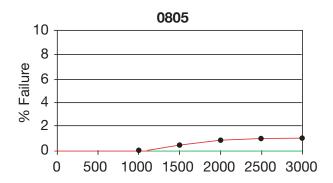
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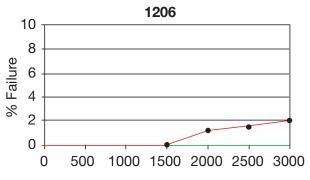
Specifications and Test Methods

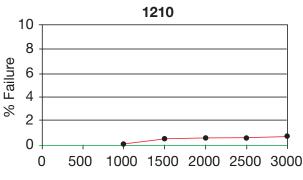


BEYOND 1000 CYCLES: TEMPERATURE CYCLE TEST RESULTS









Green = Soft Term MLCC (Flexiterm)Red = Standard MLCC

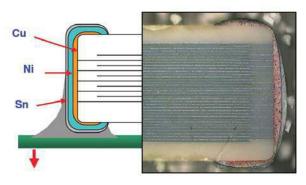
Soft Term - No Defects up to 3000 cycles

AEC-Q200 specification states 1000 cycles compared to AVX 3000 temperature cycles.

FLEXITERM® TEST SUMMARY

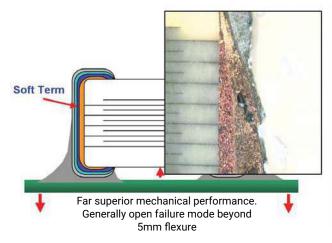
- Qualified to AEC-Q200 test/specification with the exception of using AVX 3000 temperature cycles (up to +150°C bend test quaranteed greater than 5mm).
- FLEXITERM® provides improved performance compared to standard termination systems.
- · Board bend test improvement by a factor of 2 to 4 times.
- · Temperature Cycling:
- 0% Failure up to 3000 cycles
- No ESR change up to 3000 cycle

WITHOUT SOFT TERMINATION



Major fear is of latent board flex failures.

WITH SOFT TERMINATION







Capacitance Range X8R Dielectric

	SIZE	06	03	08	305	12	06
Sc	oldering	Reflow	//Wave	Reflov	v/Wave	Reflow	/Wave
	WVDC	25V	50V	25V	50V	25V	50V
271	Cap 270	G	G				
331	(pF) 330	G	G	J	J		
471	470	G	G	J	J		
681	680	G	G	J	J		
102	1000	G	G	J	J	J	J
152	1500	G	G	J	J	J	J
182	1800	G	G	J	J	J	J
222	2200	G	G	J	J	J	J
272	2700	G	G	J	J	J	J
332	3300	G	G	J	J	J	J
392	3900	G	G	J	J	J	J
472	4700	G	G	J	J	J	J
562	5600	G	G	J	J	J	J
682	6800	G	G	J	J	J	J
822	8200	G	G	J	J	J	J
103	Cap 0.01	G	G	J	J	J	J
123	(μF) 0.012	G	G	J	J	J	J
153	0.015	G	G	J	J	J	J
183	0.018	G	G	J	J	J	J
223	0.022	G	G	J	J	J	J
273	0.027	G	G	J	J	J	J
333	0.033	G	G	J	J	J	J
393 473	0.039 0.047	G G	G G	J	J	J	J
563	0.047	G	G	N N	J N	M	J
683	0.056	G		N N	N N	M	M M
823	0.082	G		N N	N N	M	M
104	0.082			N N	N N	M	M
124	0.12			N	N	M	M
154	0.12			N	N	M	M
184	0.13			N	14	M	M
224	0.10			N		M	M
274	0.27			.,		M	M
334	0.33					M	M
394	0.39					M	
474	0.47					M	
684	0.68					.,.	
824	0.82				İ		
105	1				i e		
	WVDC	25V	50V	25V	50V	25V	50V
	SIZE	06	03	08	305	12	06
	- ==						

Letter	Α	С	Е	G	J	K	М	N	Р	Q	Х	Υ	Z	
Max. Thickness	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79	
HIICKHESS	(0.010) (0.022) (0.020)		(0.035)	(0.037)	(0.040)									
			PAPER						EMBO	SSED				

TS 16949, ISO 9001Certified



Capacitance Range X7R Dielectric

	Size			040	2				06	03					- (805						120	6				12	10		18	12		2220	
	Solderi		Ref		Wave	†		R		/Wave						w/Wa	ve				Re	eflow/					Reflov		/	Reflo		Re	eflow (
<u> </u>	WVDO						116V				200V	250V	16V	25V				250V	16V	25V				250V	1500V									100 V
221	Сар	220		C	C	1.01					2001	2001				C	2001	2001					2001	200.						001				.00 .
271	(pF)	270		C	C		1									<u> </u>																		
331	(p.)	330		c	Ċ																					\vdash								
391		390	c	Ċ	Ċ						1					1							1											
471		470	C	C	C																													
561		560	Ċ	Ċ	Ċ																													
681		680	c	c	c																													
821		820	c	c	Ċ																													
102		1000	c	Ċ	Ċ		G	G	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J	J	J	К	K	К	К	N	N			
182		1800	C	Ċ	Ċ		G	Ğ	G	G	Ğ	G	J	J	J	J	Ĵ	Ĵ	J	J	J	J	J	J	Ĵ	K	K	K	K	N	N			
222		2200	C	C	C		G	G	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J	J	J	К	K	К	К	N	N			
332		3300	c	Ċ	Ċ		G	G	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J	J	J	K	K	K	K	N	N			İ
472		4700		C	C		G	G	G	G	G	G	J	J	J	J	Ĵ	J	J	J	J	J	J	J	J	K	K	K	K	N	N			
103	Сар	0.01	C				G	G	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J	J	J	К	K	К	К	N	N			
123	(µF)	0.012	С		İ		G	G	G				J	J	J	N	N	N	J	J	J	J	J	J		К	K	К	К	N	N			
153		0.015	С				G	G	G		i –		J	J	J	N	N	N	J	J	J	J	J	J	i i	К	K	К	К	N	N			
183		0.018	С				G	G	G				J	J	J	N	N	N	J	J	J	J	J	J		К	K	К	К	N	N			
223		0.022	С				G	G	G				J	J	J	N	N	N	J	J	J	J	J	J		K	K	К	К	N	N			
273		0.027	С				G	G	G				J	J	J	N	N	N	J	J	J	J	J	J		K	K	K	K	N	N			
333		0.033	С			Ť T	G	G	G				J	J	J	N	N	N	J	J	J	J	J	J		K	K	К	К	N	N			
473		0.047					G	G	G				J	J	J	N	N	N	J	J	J	М	J	J		K	K	K	K	N	N			
563		0.056					G	G	G				J	J	J	N			J	J	J	М	J	J		K	K	K	М	N	N			
683		0.068					G	G	G				J	J	J	N			J	J	J	М	J	J		K	K	K	М	N	N			
823		0.082					G	G	G				J	J	J	N			J	J	J	М	J	J		K	K	K	M	N	N			
104		0.1	С				G	G	G				J	J	J	N			J	J	J	М	J	J		K	K	K	М	N	N			
124		0.12											J	J	N	N			J	J	М	М				K	K	K	Р	N	N			
154		0.15											М	N	N	N			J	J	М	М				K	K	K	Р	N	N			
224		0.22				G							М	N	N	N			J	М	М	Q				M	М	М	Р	N	N			
334		0.33											N	N	N	N			J	М	Р	Q				Р	Р	Р	Q	Х	Х			
474		0.47											N	N	N	N			М	М	P	Q				Р	Р	P	Q	Х	Х			
684		0.68											N	N	N	N			М	Q	Q	Q				Р	Р	Q	Х	Х	Х			
105		1											N	N	N	N			М	Q	Q	Q				Р	Q	Q	Z	Х	Х			
155		1.5											N	N					Q	Q	Q					Р	Q	Z	Z	Х	Х			
225		2.2											N	N					Q	Q	Q					Х	Z	Z	Z	Z	Z			
335		3.3																	Q	Q						Х	Z	Z	Z	Z				
475		4.7																	Q	Q						Х	Z	Z	Z	Z		$oxed{oxed}$		Z
106		10																								Z	Z	Z					Z	Z
226		22																														Z		
	WVD0		16V			10V	' 16V	25V			200V	250V	16V	25V			200V	250V	16V	25V	50V			250V	500V	16V			100 V		100 V	25V		100 V
	Size			040	2				06	03					(805						120	6				12	10		18	12		2220	

Letter	Α	С	E	G	J	K	М	N	Р	Q	Х	Υ	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER						EMBC	SSED			

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